



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

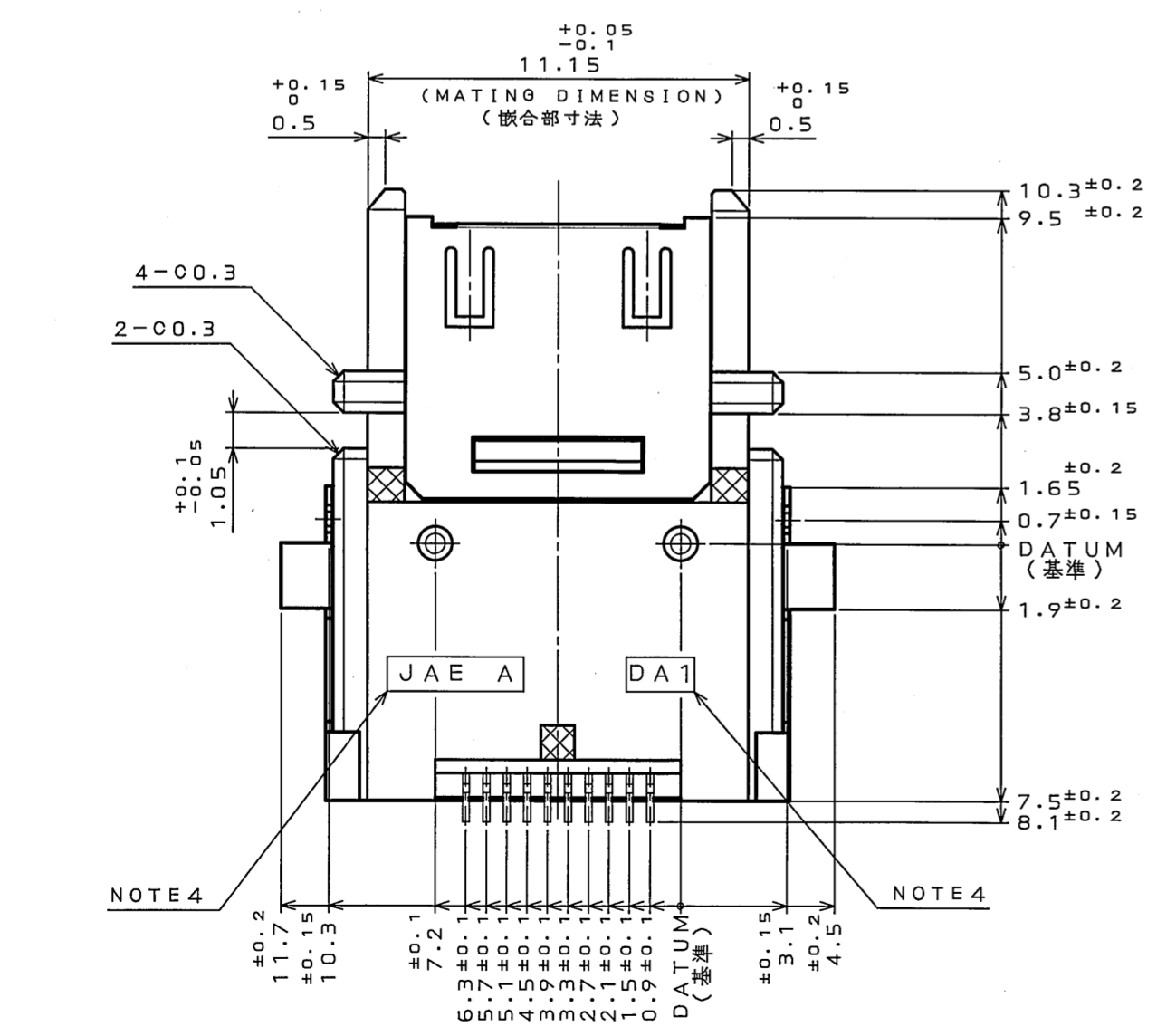
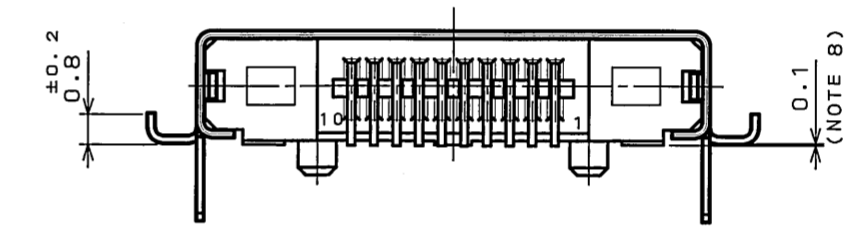
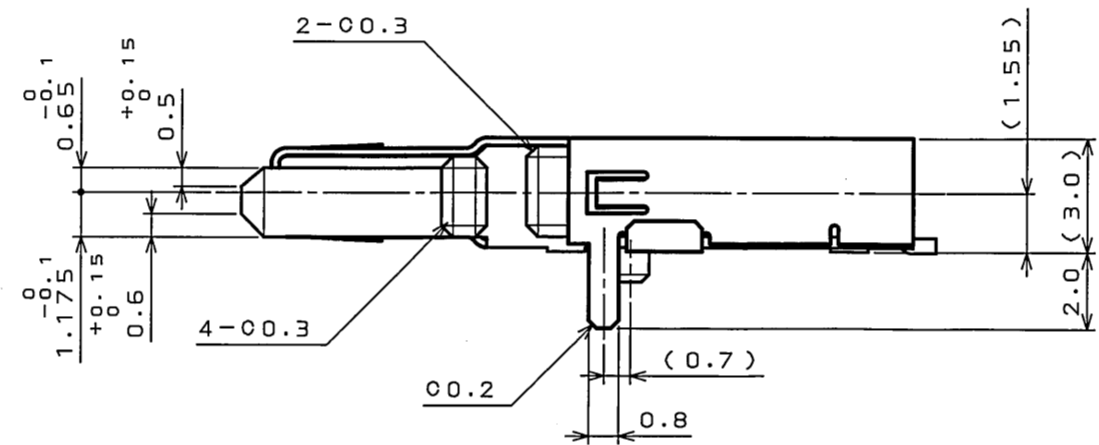
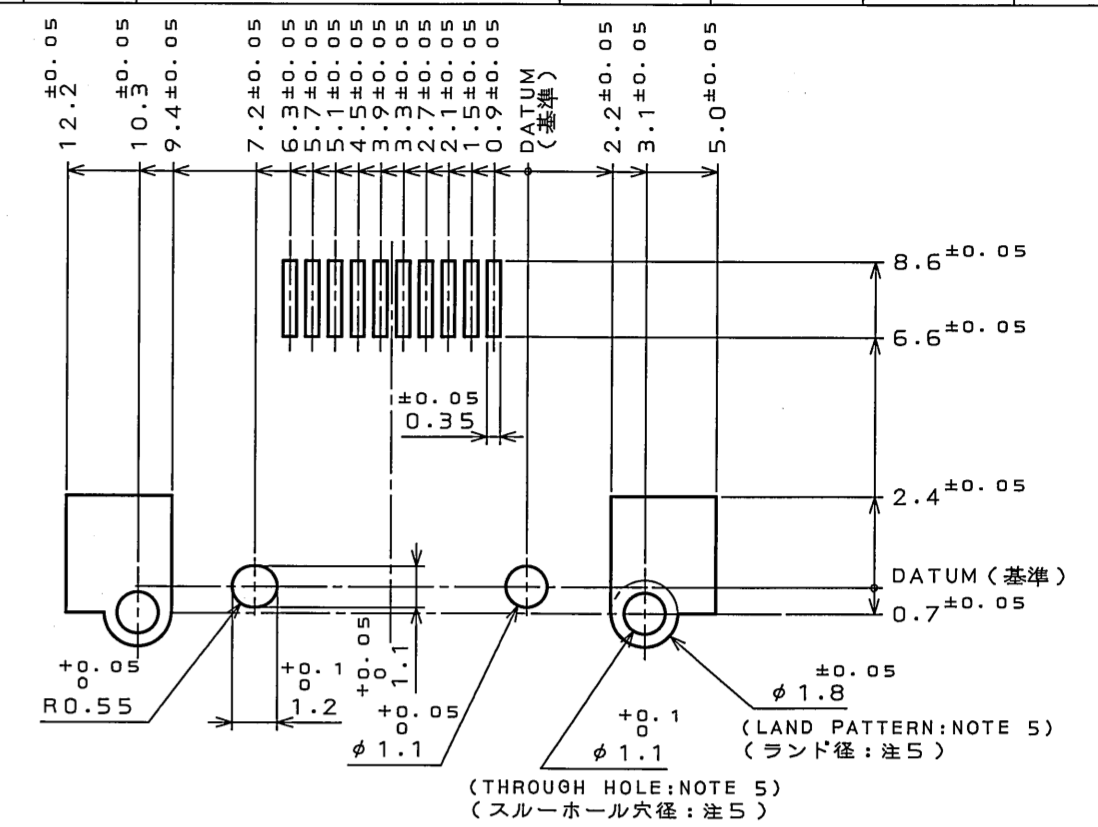
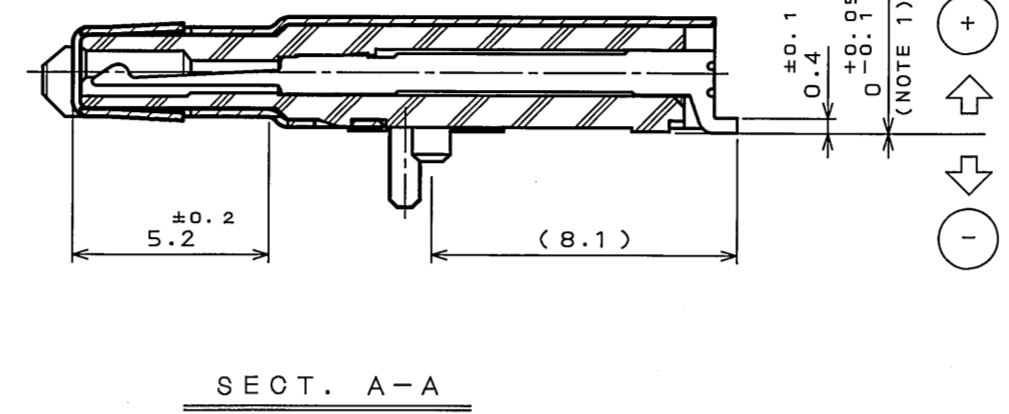
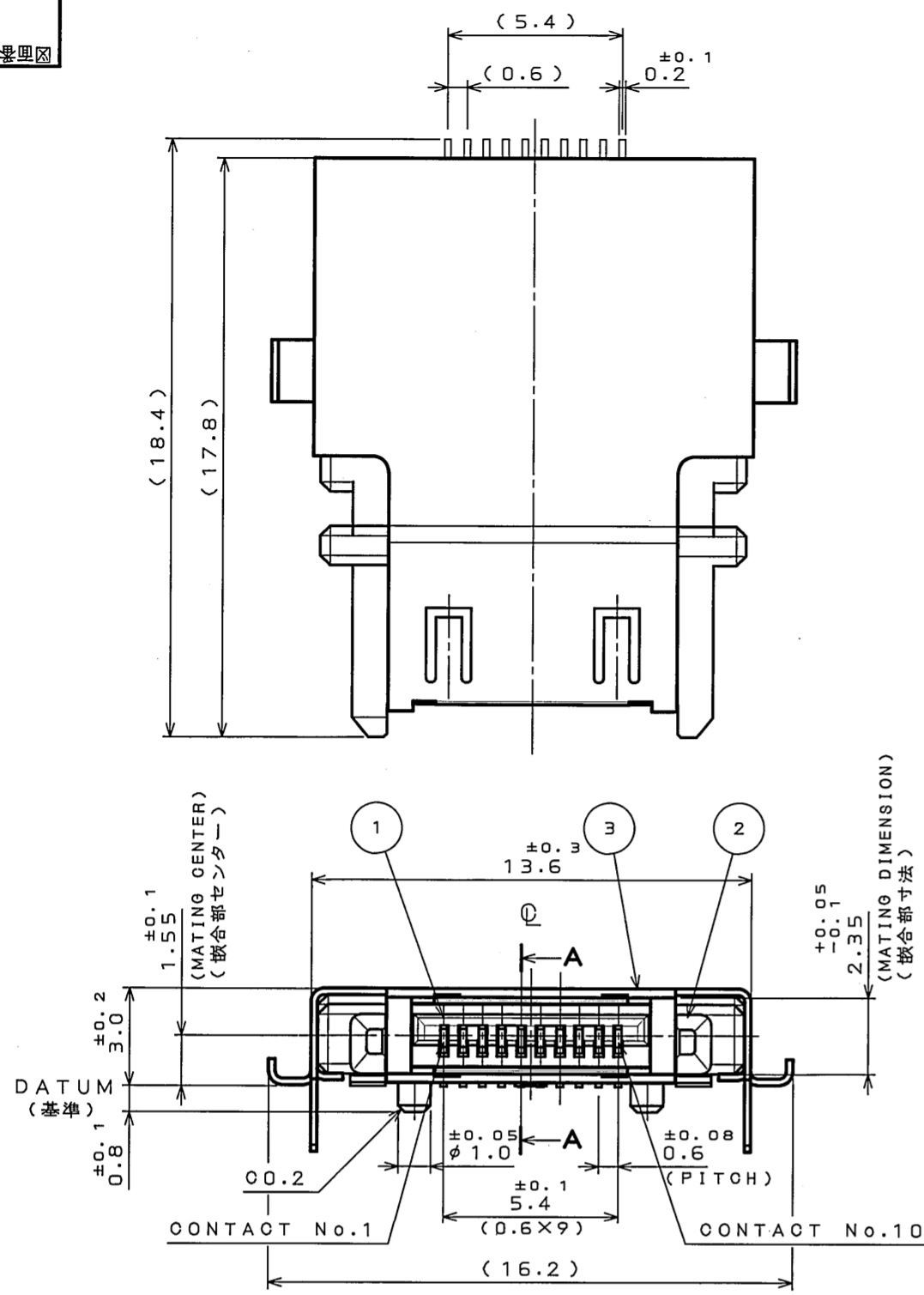
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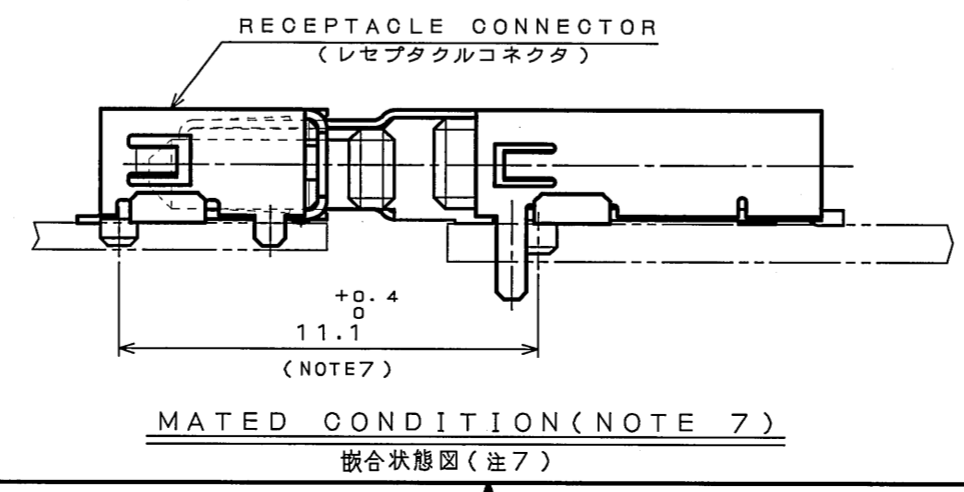


| 版数 REV. | 年月日 DATE | DCN NO. | 変更内容 DESCRIPTION | 製図 DR. | 担当 CHK. | 承認 APPD. | 承認 APPD. |
|---------|-------------|---------|------------------|--------|----------|----------|-----------|
| 2 | 16.Dec.2004 | 056414 | FINISH CHANGE | | Y.TAKAGI | | Y. Kubota |



- NOTE 1. ⊕ AND ⊖ DENOTE ARE DIRECTION OF SMT TOLERANCE. TERMINAL DIMENSION IS $0^{+0.05}$, AND DEVIATION (DIMENSION BETWEEN MINUS VALUE & PLUS VALUE) SHALL BE 0.1 MAX.
- △ 2. THE CONNECTING AREA IS PLATED WITH GOLD FLASH (0.03μmMIN) OVER Pd-Ni (0.4μmMIN) OVER NICKEL (1.5μmMIN). THE TERMINAL AREA IS PLATED WITH GOLD FLASH (0.03μmMIN) OVER NICKEL (1.5μmMIN).
3. THE SHEARED EDGES OF CONNECTOR SHELL AT THE SOLDER AREA ARE NOT PLATING.
4. COMPANY LOGO "JAE" AND PART NUMBER "DA1" ARE MARKED AS INDICATED.
5. LAND MARK BOTH SIDERS OF P.C.B. HOLE OF φ1.1 IS THROUGH HOLE PLATED.
6. THE GUIDING DIMENSIONS IN MATING IS 0.5mm MAX. IN EACH DIRECTION.
7. THE DISTANCE BETWEEN BOSS IN CRADLE CONNECTOR AND THAT IN RECEPTACLE CONNECTOR IS $11.1^{+0.4}$ mm IN MATED SITUATION.
8. THE FLOATAGE OF THE HOLD DOWN AREA IN 0.1mm MAX WHILE PUT ON THE P.C.B.

- 注 1. SMT公差部のプラス、マイナスの方向を示す。端子寸法は $0^{+0.05}$ であり公差内におけるバラツキ (1コネクタ内のMAX値とMIN値の差) は0.1以下とする。
- △ 2. 接触部は、ニッケル (1.5μm以上) 上パラジウムニッケル (0.4μm以上) 上金フラッシュメッキ (0.03μm以上)、結線部は、ニッケル (1.5μm以上) 上金フラッシュメッキ (0.03μm以上) である。
3. 本コネクタシェル半田付部破断面には、メッキは施されません。
4. 図示の位置に社標 "JAE" 及び品名 "DA1" を表示する。
5. ランドは基板の両面に設けること。又、φ1.1の穴はスルーホールメッキであること。
6. 嵌合時のガイド量は各方向0.5以下であること。
7. 嵌合状態での基準間寸法は $11.1^{+0.4}$ であること。
8. 基板にのせた状態でホールドダウンの浮きは0.1以下のこと。



| | | | | | |
|---------------------|----------------|---------------------|---|------------|-------------|
| 3 | SHELL | 1 | STAINLESS STEEL (LEAD FREE) TIN/TIN ALLOY | | |
| 2 | INSULATOR | 1 | PPS | | UL94V-0 |
| 1 | CONTACT | 10 | COPPER ALLOY | NOTE 2 | |
| 符号 NO. | 名称 DESCRIPTION | 個数 QTY. | 材料 MATERIAL | 仕上 FINISH | 備考 REMARKS |
| 仕様書 (SPECIFICATION) | JACS-3192 | 第1版 (ORIGINAL DATE) | 3.Mar.2003 | 尺 (SCALE) | 5:1 |
| 製図 DR. | M.HIRAKI | シリーズ (SERIES) | DA1 | 名称 (TITLE) | DA1B010H92E |
| 担当 CHK. | Y.TAKAGI | 承認 APPD. | Y.KUBOTA | 質量 (MASS) | |
| 寸法 (DIMENSION) | 公差 (TOLERANCE) | 角度 (ANGLES) | | | |
| . ±0.8 | X° ± | | | | |
| .X ±0.4 | X° ± | | | | |
| .XX ±0.1 | | | | | |
| .XXX ± | | | | | |

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